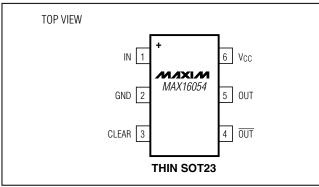
General Description

The MAX16054 is a pushbutton on/off controller with a single switch debouncer and built-in latch. It accepts a noisy input from a mechanical switch and produces a clean latched digital output after a factory-fixed qualification delay.

The MAX16054 eliminates contact bounce during switch opening and closing. The state of the output changes only when triggered by the falling edge of the debounced switch input; the output remains unchanged on the rising edge of the input. Robust switch inputs handle $\pm 25V$ levels and are $\pm 15kV$ ESD protected for use in harsh industrial environments. The MAX16054 features a complementary output, OUT, which is the inverted state of OUT. An asynchronous CLEAR input allows an external signal to force the output flip-flop low. Undervoltage-lockout circuitry ensures that OUT is in the off state upon power-up. The MAX16054 requires no external components, and its low supply current makes it ideal for use in portable equipment.

The MAX16054 operates from a +2.7V to +5.5V single supply. The MAX16054 is offered in a 6-pin thin SOT23 package and operates over the -40°C to +125°C automotive temperature range.





Features

- Robust Inputs Can Handle Power Supplies Up to ±25V
- ±15kV ESD Protection
- Latched Output
- Low 7µA Supply Current
- Operates from 2.7V to 5.5V
- ♦ -40°C to +125°C Temperature Range
- Thin SOT23 Package

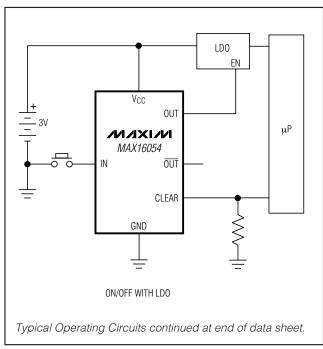
_Ordering Information

PART	TEMP RANGE	PIN- PACKAGE	TOP MARK
MAX16054AZT+T	-40°C to +125°C	6 Thin SOT23	+AADU

+Denotes a lead-free package.

T = Tape and reel package. Devices are offered in 2.5k unit increments.

Typical Operating Circuits



M/IXI/M

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ABSOLUTE MAXIMUM RATINGS

V _{CC} to GND	-0.3V to +6V
IN to GND	30V to +30V
CLEAR to GND	
OUT, OUT to GND	0.3V to (V _{CC} + 0.3V)
Short-Circuit Duration	
OUT, OUT to GND	Continuous

Continuous Power Dissipation ($T_A = +70^{\circ}$ C) 6-Pin Thin SOT23 (derate 9.1mW/°C at +70°C) (Note 1).....727mW Operating Temperature Range-40°C to +125°C Maximum Junction Temperature+150°C Storage Temperature Range-60°C to +150°C Lead Temperature (soldering, 10s).....+300°C

Note 1: As per JEDEC 51 standard, multilayer board (PCB).

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

ELECTRICAL CHARACTERISTICS

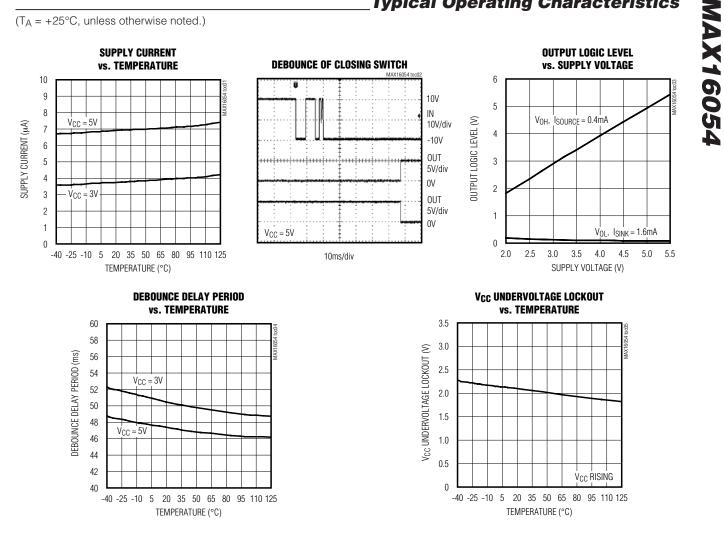
 $(V_{CC} = +2.7V \text{ to } +5.5V, T_A = T_J = -40^{\circ}\text{C} \text{ to } +125^{\circ}\text{C}, \text{ unless otherwise noted. Typical values are at } V_{CC} = +5V, T_A = +25^{\circ}\text{C}.)$ (Note 2)

PARAMETER	SYMBOL	CONDITIONS		MIN	ТҮР	МАХ	UNITS	
Operating Voltage Range	V _{CC}	(Note 3)		2.7		5.5	V	
Supply Current	Icc	$V_{CC} = 5V$, $I_{OUT} = I_{\overline{OUT}} = 0$, IN not connected			7	20	μA	
	t _{DP}	$T_A = +25^{\circ}C$		20	50	80	ms	
Debounce Duration		$T_A = -40^{\circ}C \text{ to } + 125^{\circ}C$	°C	5	50	99		
	VIL					0.65		
IN Threshold	VIH	$V_{CC} = 5V$		2.5			V	
	VIH	$V_{CC} = 2.7V$		2.0			1	
IN Hysteresis					420		mV	
IN Pullup Resistance				32	63	100	kΩ	
IN Current	lin	$V_{IN} = +25V$				+1.5	mA	
in Current	IIN	$V_{IN} = -25V$		-1.5			mA	
IN Voltage Range	VIN			-25		+25	V	
Undervoltage-Lockout Threshold	Vuvlo	V _{CC} falling			1.8	2.4	V	
OUT/OUT Output Voltage	Vol	$I_{SINK} = 1.6 mA$				0.4	v	
	VOH	ISOURCE = 0.4mA		V _{CC} - 1.0			v	
CLEAR Threshold	VCLEAR_IL					0.7		
	VCLEAR_IH	$V_{CC} = 5V$		2.4			V	
		$V_{CC} = 2.7V$		2.0				
CLEAR Input Current	ICLEAR			-1		+1	μA	
CLEAR High to OUT Low Propagation Delay	tco	$R_L = 10k\Omega, C_L = 10$	0pF			200	ns	
ESD CHARACTERISTICS								
ESD Protection		IN	IEC 61000-4-2 Air Discharge		±15			
			IEC 61000-4-2 Contact Discharge		±8		kV	
			Human Body Model		±15			

Note 2: All devices are 100% production tested at $T_A = +25^{\circ}C$. Specifications over temperature limits are guaranteed by design. **Note 3:** OUT is guaranteed to be low for $1.0V \le V_{CC} \le V_{UVLO}$.

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Typical Operating Characteristics



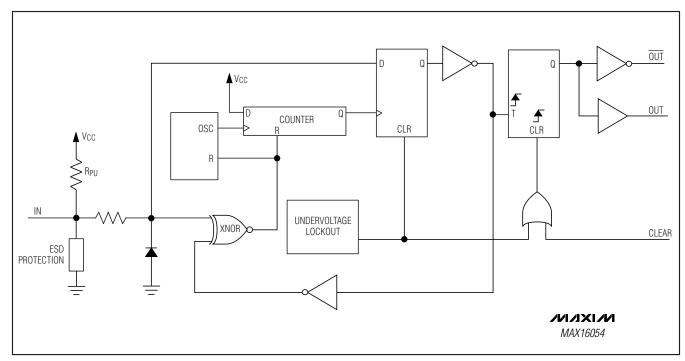
Pin Description

PIN	NAME	FUNCTION	
1	IN	Switch Toggle Input. IN features a -25V to +25V maximum input range and includes an internal $63k\Omega$ pullup resistor to V _{CC} . Connect a pushbutton from IN to GND.	
2	GND	Ground	
3	CLEAR	Clear Input. Pull CLEAR high to force OUT low. Connect CLEAR to GND if unused.	
4	OUT	Active-Low CMOS Output	
5	OUT	Active-High CMOS Output	
6	V _{CC}	+2.7V to +5.5V Supply Input. In noisy environments, bypass V _{CC} to GND with a 0.1 μ F or greater ceramic capacitor.	

$(T_A = +25^{\circ}C, unless otherwise noted.)$

MAX16054

Functional Diagram



Detailed Description

Theory of Operation

The MAX16054 creates a push-on, push-off function using a momentary-contact normally open SPST switch. The high-to-low transition that occurs when closing the switch causes OUT to go high and OUT to go low. The output state remains latched after the switch is released/opened. Closing the switch again causes OUT to go low and OUT to go high.

Debounce circuitry eliminates the extraneous level changes that result from interfacing with mechanical switches (switch bounce). Virtually all mechanical switches bounce upon opening and closing. The bounce when a switch opens or closes is eliminated by requiring that the sequentially clocked input remains in the same state for a number of sampling periods. The output does not change state from high-to-low or lowto-high until the input is stable for at least 50ms (typ).

The *Functional Diagram* shows the functional blocks consisting of an on-chip oscillator, counter, exclusive-NOR gate, a D flip-flop, and a T (toggle) flip-flop. When the pushbutton input does not equal the internal debounced button state (the Q output of the D flip-flop), the XNOR gate issues a counter reset. When the switch input state is stable for the full qualification period, the counter clocks the D flip-flop, changing the internal pushbutton state. The Q output of the D flip-flop is connected to a toggle flip-flop that toggles when the internal pushbutton state goes through a high-to-low transition. Figure 1 shows the typical opening and closing switch debounce operation.

A rising pulse at CLEAR resets the T flip-flop and pulls OUT low and OUT high.

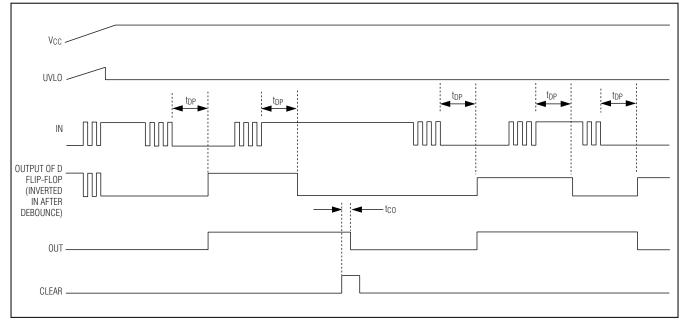


Figure 1. MAX16054 Timing Diagram

Undervoltage Lockout

The undervoltage-lockout circuitry ensures that the outputs are at the correct state on power-up. While V_{CC} is less than the 2.1V (typ) undervoltage threshold and greater than 1.0V, OUT remains low and transitions at IN are ignored.

Robust Switch Input

The switch input (IN) has overvoltage clamping diodes to protect against damaging fault conditions. Switch input voltages can safely swing $\pm 25V$ to ground. Proprietary ESD-protection structures protect against high ESD encountered in harsh industrial environments, membrane keypads, and portable applications. They are designed to withstand $\pm 15kV$ per the IEC 61000-4-2 Air-Gap Discharge test and $\pm 8kV$ per the IEC 61000-4-2 Contact-Discharge test.

Since there is a $63k\Omega$ (typ) pullup resistor connected to IN, driving the input to -25V draws approximately 0.5mA from the V_{CC} supply. Driving the input to +25V causes approximately 0.32mA of current to flow back into the V_{CC} supply. If the total system V_{CC} supply current is less than the current flowing back into the V_{CC} supply,

 V_{CC} rises above normal levels. In some low-current systems, a zener diode on V_{CC} may be required.

±15kV ESD Protection

ESD-protection structures are incorporated on all pins to protect against electrostatic discharges encountered during handling and assembly. The MAX16054 has extra protection against static electricity to protect against ESD of ± 15 kV at the switch input without damage. The ESD structures withstand high ESD in all states: normal operation, shutdown, and powered down. A design advantage of the MAX16054 is that it continues working without latchup after an ESD event, which eliminates the need to power-cycle the device.

ESD protection can be tested in various ways; this product is characterized for protection to the following limits:

- 1) ±15kV using the Human Body Model.
- ±8kV using the Contact-Discharge method specified in IEC 61000-4-2.
- 3) ±15kV using the IEC 61000-4-2 Air-Gap method.

MAX16054

Human Body Model

Figure 2a shows the Human Body Model, and Figure 2b shows the current waveform it generates when discharged into a low impedance. This model consists of a 100pF capacitor charged to the ESD voltage of interest, which is then discharged into the test device through a $1.5k\Omega$ resistor.

IEC 61000-4-2 standard covers ESD testing and performance of finished equipment; it does not specifically refer to integrated circuits. The MAX16054 helps in the design of equipment that meets IEC 61000-4-2, without the need for additional ESD-protection components.

The major difference between tests done using the Human Body Model and IEC 61000-4-2 is higher peak current in IEC 61000-4-2, because series resistance is

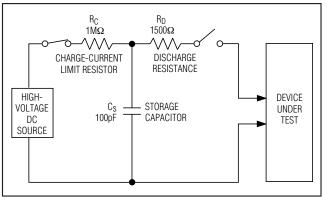


Figure 2a. Human Body ESD Test Model

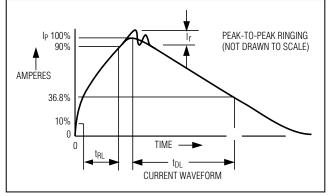


Figure 2b. Human Body Current Waveform

lower in the IEC 61000-4-2 model. Hence, the ESD withstand voltage measured to IEC 61000-4-2 is generally lower than that measured using the Human Body Model. Figure 3a shows the IEC 61000-4-2 model, and Figure 3b shows the current waveform for the IEC 61000-4-2 ESD Contact-Discharge test.

The Air-Gap test involves approaching the device with a charged probe. The Contact-Discharge method connects the probe to the device before the probe is energized.

Machine Model

The Machine Model for ESD tests all pins using a 200pF storage capacitor and zero discharge resistance. Its objective is to emulate the stress caused by contact that occurs with handling and assembly during manufacturing.

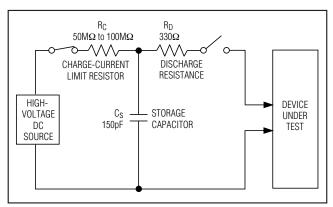


Figure 3a. IEC 61000-4-2 ESD Test Model

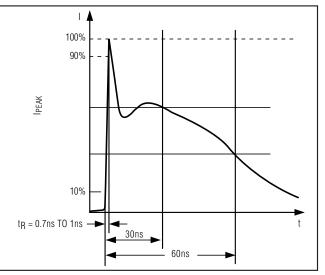
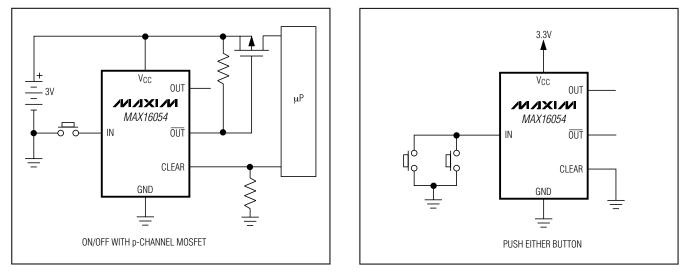
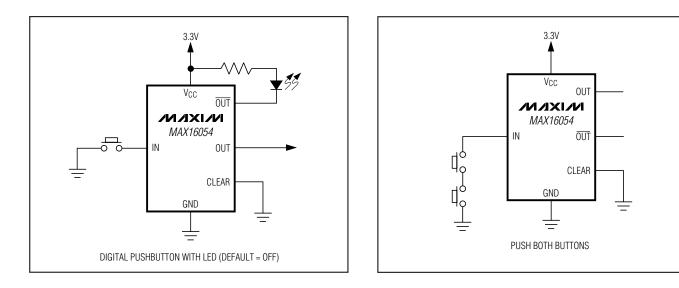


Figure 3b. IEC 61000-4-2 ESD Generator Current Waveform

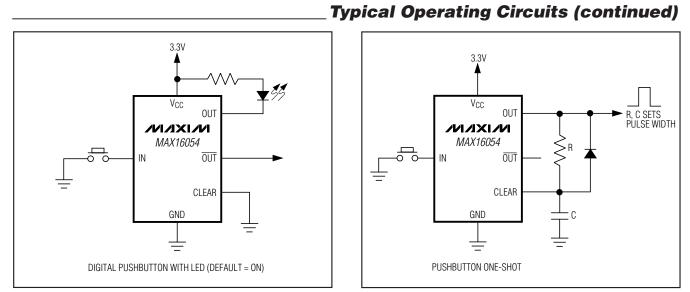


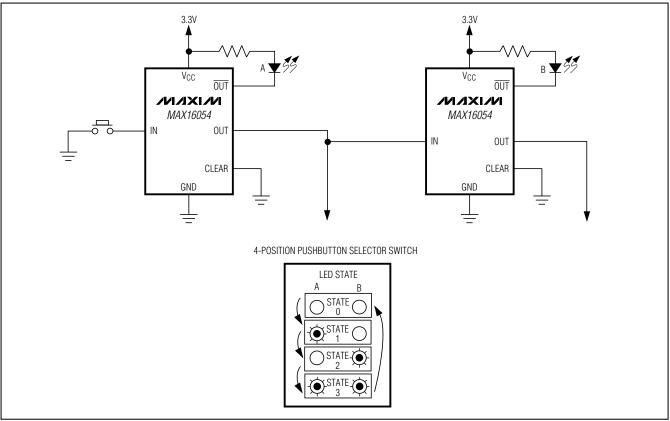


Typical Operating Circuits (continued)









Chip Information

PROCESS: BICMOS

_Package Information

For the latest package outline information, go to **www.maxim-ic.com/packages**.

PACKAGE TYPE	PACKAGE CODE	DOCUMENT NO.
6 Thin SOT23	Z6-1	<u>21-0114</u>

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